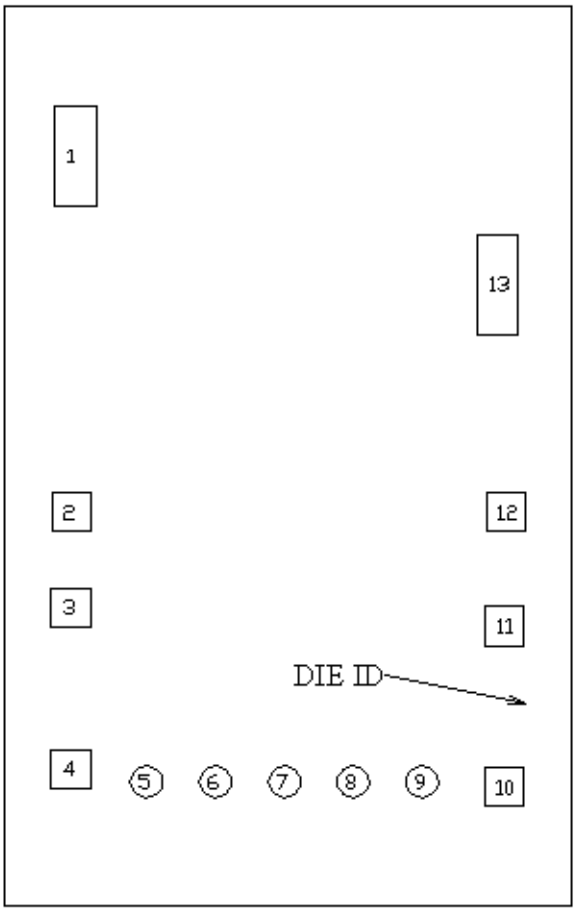
LM2621 MDC MWC
LOW INPUT VOLTAGE, STEP-UP DC-DC CONVERTER

February 12,2002

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		**General Die Information**	
Physical Die Identification	LM2621A	Bond Pad Opening Size (min)	76µm x 76µm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1346µm x 2134µm 53mils x 84mils	Back Side Connection	Floating
Thickness	254µm Nominal		
Min Pitch	182µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection

SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES X	Y	PAD SIZE X		Y
PGND	1	-506	712	102	x	241
EN	2	-515	-134	94	x	94
FREQ	3	-516	-359	94	x	94
FB	4	-516	-743	94	x	94
NC	5	-337	-774	76	x	76
NC	6	-173	-774	76	x	76
NC	7	-9	-774	76	x	76
NC	8	154	-774	76	x	76
NC	9	318	-774	76	x	76
SGND	10	512	-787	94	x	94
VDD	11	515	-404	94	x	94
BOOT	12	516	-134	94	x	94
SW	13	497	406	98	x	241

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